

DFR1A THRU DFR1M

1.0A Surface Mount Fast
Recovery Rectifiers-50-1000V

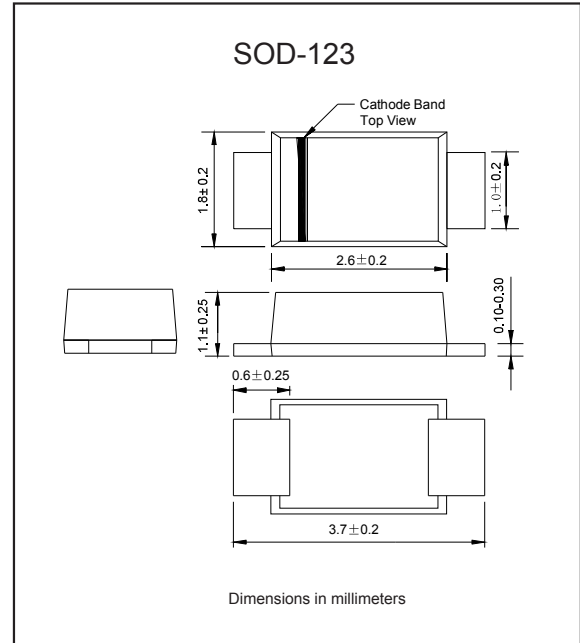
Features

- ◆ Glass passivated device
- ◆ Ideal for surface mounted applications
- ◆ Low reverse leakage
- ◆ Metallurgically bonded construction
- ◆ High temperature soldering guaranteed:
250°C/10 seconds, 0.375" (9.5mm) lead length,
5 lbs. (2.3kg) tension
- ◆ Compliant to RoHS Directive 2011/65/EU
- ◆ Compliant to Halogen-free

Mechanical data

- ◆ **Case**: JEDEC SOD-123 molded plastic body over passivated chip
- ◆ **Terminals**: Plated axial leads, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity**: Color band denotes cathode end
- ◆ **Mounting Position**: Any
- ◆ **Weight**: 0.0007 ounce, 0.02 grams

Package outline

Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.2	I_O			1.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I_{FSM}			25	A
Reverse current	$V_R = V_{RRM} \quad T_A = 25^\circ\text{C}$	I_R			5.0	μA
	$V_R = V_{RRM} \quad T_A = 100^\circ\text{C}$				50	
Thermal resistance	Junction to ambient NOTE 1	$R_{\theta JA}$		50		$^\circ\text{C/W}$
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C_J		15		pF
Storage temperature		T_{STG}	-65		+150	$^\circ\text{C}$

SYMBOLS	V _{RRM} ^{*1} (V)	V _{RMS} ^{*2} (V)	V _R ^{*3} (V)	V _F ^{*4} (V)	t _{rr} ^{*5} (ns)	Operating temperature T _J , (°C)
DFR1A	50	35	50	1.30	150	-55 to +150
DFR1B	100	70	100			
DFR1D	200	140	200			
DFR1G	400	280	400			
DFR1J	600	420	600			
DFR1K	800	560	800			
DFR1M	1000	700	1000			

- *1 Repetitive peak reverse voltage
 *2 RMS voltage
 *3 Continuous reverse voltage
 *4 Maximum forward voltage@ $I_F=1.0\text{A}$
 *5 Maximum Reverse recovery time, note 2

Note: 1.P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas
 2. Reverse recovery time test condition, $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{RR}=0.25\text{A}$

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Rating and characteristic curves (DFR1A THRU DFR1M)

FIG.1-TYPICAL FORWARD

CHARACTERISTICS

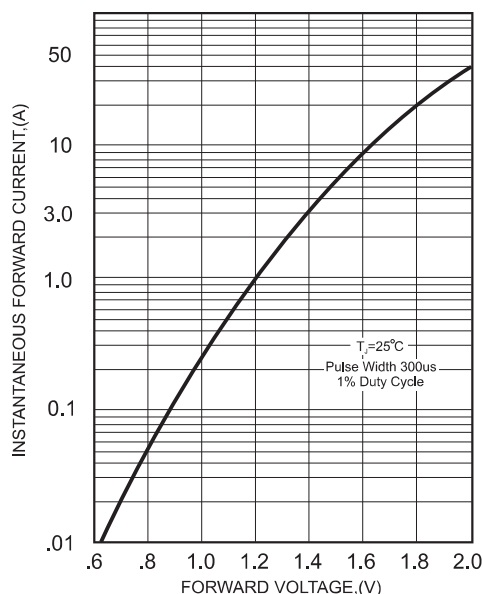


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

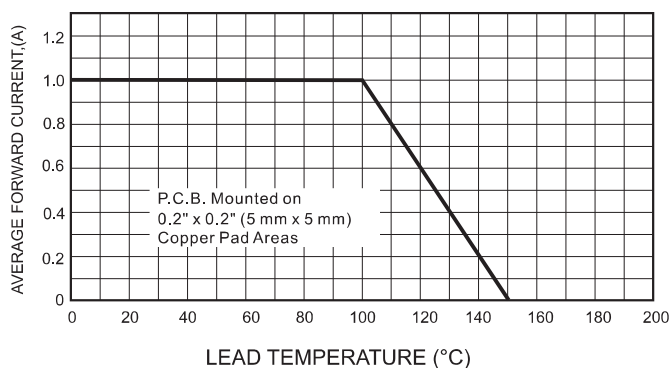


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

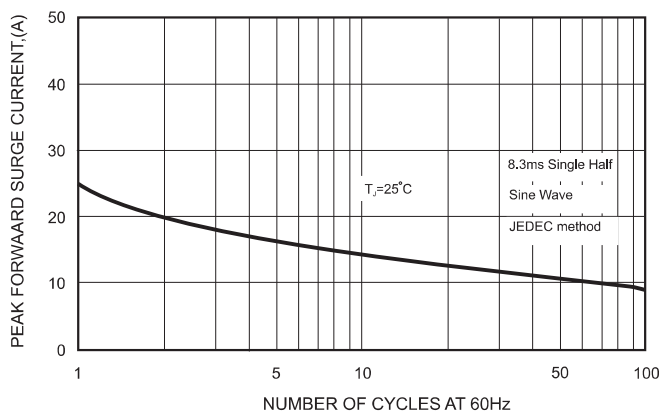
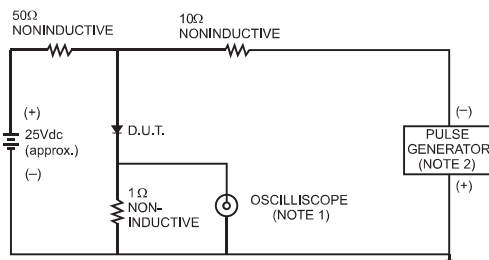


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE

RECOVERY TIME CHARACTERISTICS



NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm, 22pF.

2. Rise Time= 10ns max., Source Impedance= 50 ohms.

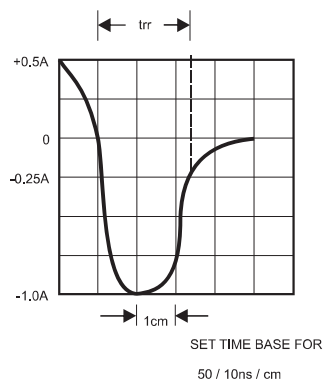
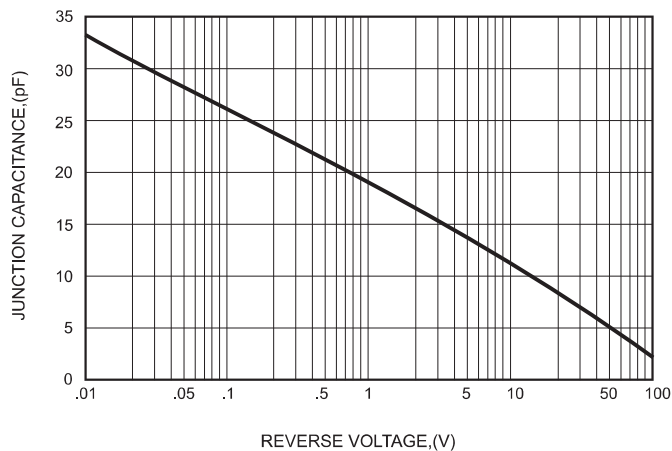
SET TIME BASE FOR
50 / 10ns / cm

FIG.5-TYPICAL JUNCTION CAPACITANCE



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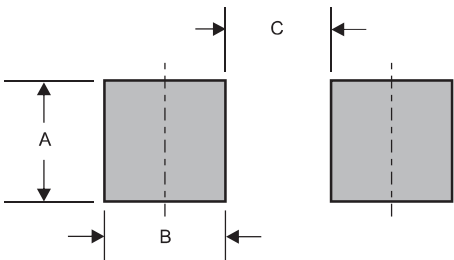
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
DFR1A	F 1
DFR1B	F 2
DFR1D	F 3
DFR1G	F 4
DFR1J	F 5
DFR1K	F 6
DFR1M	F 7

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-123	0.075 (1.90)	0.055 (1.40)	0.075 (1.90)